

## **RoseStreet Labs Announces 3D & MEMs Packaging R&D Laboratory and Alliance with SUSS MicroTec**

PHOENIX, Arizona, August 9, 2005—RoseStreet Labs announced today the opening of their 3D Research and Development laboratory for next generation semiconductor packaging. RoseStreet Labs and its subsidiary, FlipChip International, develop new materials and processes for packaging utilized in leading wireless products. RSL also announced an alliance with SUSS MicroTec. SUSS MicroTec's full suite of lithography and 3D packaging equipment was selected for RoseStreet's laboratory.

RoseStreet Labs is headquartered in Phoenix, AZ with capabilities in polymer development, metal deposition, lithography, 3D packaging, System-in-Package, MEMs packaging and interconnect development. RoseStreet Labs R&D offers contract R&D services in addition to its internal R&D work in support of FlipChip International's globally recognized flip chip and wafer level packaging product lines.

Michael Gustafson of SUSS MicroTec said, "We are very excited about our alliance with RoseStreet Labs and FlipChip International. We are pleased that after careful evaluation RoseStreet Labs chose SUSS due to our superior process and cost performance results. We look forward to the continuation of this mutually beneficial relationship."

Bob Forcier, President & CEO of RoseStreet Labs, said "This opening of our new R&D lab and our alliance with our close partner, SUSS MicroTec, is part of our five year technology roadmap to provide next generation solutions to our valued customers in the areas of wafer level MEMs, sensor, System-In-Package and advanced 3D packaging. We are very excited by this milestone and will continue to invest in advanced technology."

Dr. Joan K. Vrtis, CTO of RoseStreet Labs, said "We are very pleased to have such a strong technical alliance with SUSS MicroTec. The opportunity to expand RoseStreet Labs R&D capabilities in photolithography, MEMs & 3D structures strengthens our position to aggressively execute to RoseStreet's technology roadmap."

### **About RoseStreet Labs**

RoseStreet Labs, LLC, is a supplier of products and services for wireless infrastructure and sensors in the life science, renewable energy and homeland security markets. RoseStreet Labs actively provides interconnect and assembly R&D for next generation products and is the parent to FlipChip International, LLC., the global leader in flip chip bumping, wafer-level packaging, semiconductor dicing, tape & reel, and known-good-die sales. RoseStreet Labs and FlipChip International are located in Phoenix, Arizona.

### **About SUSS MicroTec**

SUSS MicroTec is a world leading supplier of precision technology providing innovative solutions for markets including Advanced Packaging, MEMS Nanotechnology, Compound Semiconductor, Silicon-

On-Insulator, and 3D Interconnect. SUSS MicroTec manufactures a complete line of photoresist and dielectric coat/bake/develop systems, microlithography exposure systems, wafer and device bonders, probers, photomasks, cleaners and etchers.

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